

# MUN2234, MMUN2234L, MUN5234, DTC124XE, DTC124XM3, NSBC124XF3



## Digital Transistors (BRT) R1 = 22 kΩ, R2 = 47 kΩ

### NPN Transistors with Monolithic Bias Resistor Network

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

#### Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

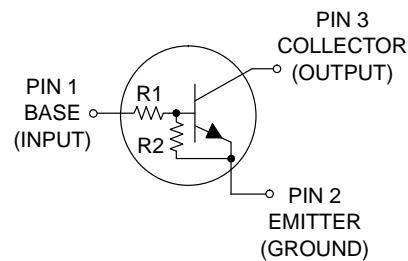
Rating	Symbol	Max	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	Vdc
Collector-Emitter Voltage	V <sub>CEO</sub>	50	Vdc
Collector Current – Continuous	I <sub>C</sub>	100	mAdc
Input Forward Voltage	V <sub>IN(fwd)</sub>	40	Vdc
Input Reverse Voltage	V <sub>IN(rev)</sub>	8	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

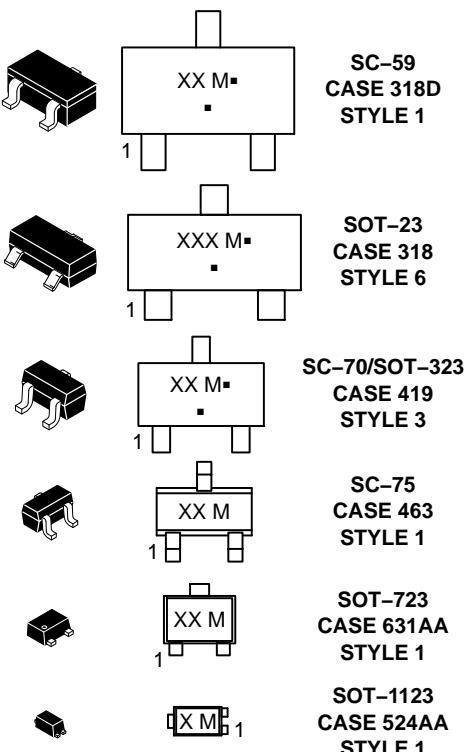
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#### PIN CONNECTIONS



#### MARKING DIAGRAMS



XXX = Specific Device Code  
M = Date Code\*  
- = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

#### ORDERING INFORMATION

See detailed ordering, marking, and shipping information in the package dimensions section on page 2 of this data sheet.

# MUN2234, MMUN2234L, MUN5234, DTC124XE, DTC124XM3, NSBC124XF3

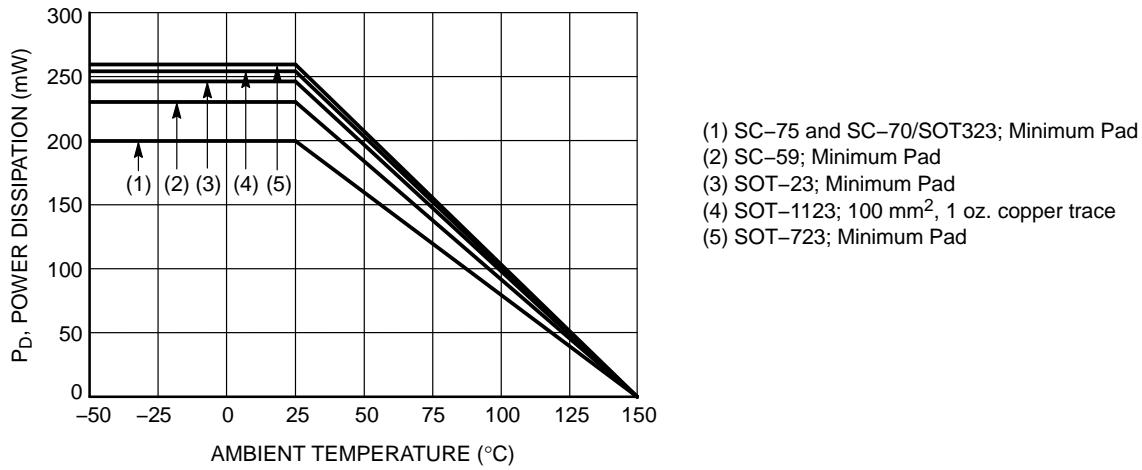
**Table 1. ORDERING INFORMATION**

Device	Part Marking	Package	Shipping <sup>†</sup>
MUN2234T1G	8L	SC-59 (Pb-Free)	3000 / Tape & Reel
MMUN2234LT1G, SMMUN2234LT1G*	A8L	SOT-23 (Pb-Free)	3000 / Tape & Reel
MUN5234T1G, NSVMUN5234T1G*	8L	SC-70/SOT-323 (Pb-Free)	3000 / Tape & Reel
DTC124XET1G	8L	SC-75 (Pb-Free)	3000 / Tape & Reel
DTC124XM3T5G	8L	SOT-723 (Pb-Free)	8000 / Tape & Reel
NSBC124XF3T5G	J (180°)**	SOT-1123 (Pb-Free)	8000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

\*\*(xx°) = Degree rotation in the clockwise direction.



**Figure 1. Derating Curve**

# MUN2234, MMUN2234L, MUN5234, DTC124XE, DTC124XM3, NSBC124XF3

Table 2. THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
<b>THERMAL CHARACTERISTICS (SC-59) (MUN2234)</b>			
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	230 338	mW
Derate above $25^\circ\text{C}$		1.8 2.7	$\text{mW}/^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	540 370	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	264 287	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$
<b>THERMAL CHARACTERISTICS (SOT-23) (MMUN2234L)</b>			
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	246 400	mW
Derate above $25^\circ\text{C}$		2.0 3.2	$\text{mW}/^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	508 311	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	174 208	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$
<b>THERMAL CHARACTERISTICS (SC-70/SOT-323) (MUN5234)</b>			
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	202 310	mW
Derate above $25^\circ\text{C}$		1.6 2.5	$\text{mW}/^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	618 403	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	280 332	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$
<b>THERMAL CHARACTERISTICS (SC-75) (DTC124XE)</b>			
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	200 300	mW
Derate above $25^\circ\text{C}$		1.6 2.4	$\text{mW}/^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	600 400	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$
<b>THERMAL CHARACTERISTICS (SOT-723) (DTC124XM3)</b>			
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	260 600	mW
Derate above $25^\circ\text{C}$		2.0 4.8	$\text{mW}/^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	480 205	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$

1. FR-4 @ Minimum Pad.
2. FR-4 @ 1.0 x 1.0 Inch Pad.
3. FR-4 @  $100 \text{ mm}^2$ , 1 oz. copper traces, still air.
4. FR-4 @  $500 \text{ mm}^2$ , 1 oz. copper traces, still air.

Table 2. THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
<b>THERMAL CHARACTERISTICS (SOT-1123) (NSBC123XF3)</b>			
Total Device Dissipation $T_A = 25^\circ\text{C}$	$P_D$	254 297 2.0 2.4	mW $\text{mW}/^\circ\text{C}$
Derate above $25^\circ\text{C}$			
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	493 421	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Lead	$R_{\theta JL}$	193	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{\text{stg}}$	-55 to +150	$^\circ\text{C}$

1. FR-4 @ Minimum Pad.
2. FR-4 @ 1.0 x 1.0 Inch Pad.
3. FR-4 @ 100 mm<sup>2</sup>, 1 oz. copper traces, still air.
4. FR-4 @ 500 mm<sup>2</sup>, 1 oz. copper traces, still air.

Table 3. ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Collector–Base Cutoff Current ( $V_{CB} = 50 \text{ V}$ , $I_E = 0$ )	$I_{CBO}$	–	–	100	nAdc
Collector–Emitter Cutoff Current ( $V_{CE} = 50 \text{ V}$ , $I_B = 0$ )	$I_{CEO}$	–	–	500	nAdc
Emitter–Base Cutoff Current ( $V_{EB} = 6.0 \text{ V}$ , $I_C = 0$ )	$I_{EBO}$	–	–	0.13	mAdc
Collector–Base Breakdown Voltage ( $I_C = 10 \mu\text{A}$ , $I_E = 0$ )	$V_{(BR)CBO}$	50	–	–	Vdc
Collector–Emitter Breakdown Voltage (Note 5) ( $I_C = 2.0 \text{ mA}$ , $I_B = 0$ )	$V_{(BR)CEO}$	50	–	–	Vdc

**ON CHARACTERISTICS**

DC Current Gain (Note 5) ( $I_C = 5.0 \text{ mA}$ , $V_{CE} = 10 \text{ V}$ )	$h_{FE}$	80	150	–	
Collector – Emitter Saturation Voltage (Note 5) ( $I_C = 10 \text{ mA}$ , $I_B = 1.0 \text{ mA}$ )	$V_{CE(\text{sat})}$	–	–	0.25	Vdc
Input Voltage (off) ( $V_{CE} = 5.0 \text{ V}$ , $I_C = 100 \mu\text{A}$ )	$V_{i(\text{off})}$	–	0.9	0.5	Vdc
Input Voltage (on) ( $V_{CE} = 0.3 \text{ V}$ , $I_C = 2.0 \text{ mA}$ )	$V_{i(\text{on})}$	2.0	1.2	–	Vdc
Output Voltage (on) ( $V_{CC} = 5.0 \text{ V}$ , $V_B = 2.5 \text{ V}$ , $R_L = 1.0 \text{ k}\Omega$ )	$V_{OL}$	–	–	0.2	Vdc
Output Voltage (off) ( $V_{CC} = 5.0 \text{ V}$ , $V_B = 0.5 \text{ V}$ , $R_L = 1.0 \text{ k}\Omega$ )	$V_{OH}$	4.9	–	–	Vdc
Input Resistor	$R_1$	15.4	22	28.6	k $\Omega$
Resistor Ratio	$R_1/R_2$	0.38	0.47	0.56	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS**  
**MUN2234, MMUN2234L, MUN5234, DTC124XE, DTC124XM3**

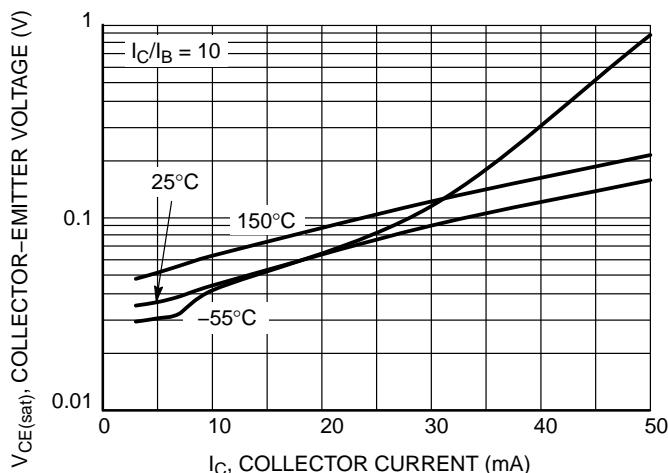


Figure 2.  $V_{CE(sat)}$  vs.  $I_C$

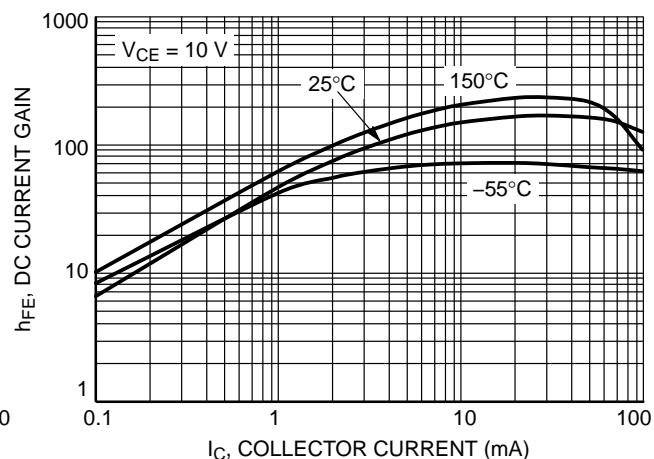


Figure 3. DC Current Gain

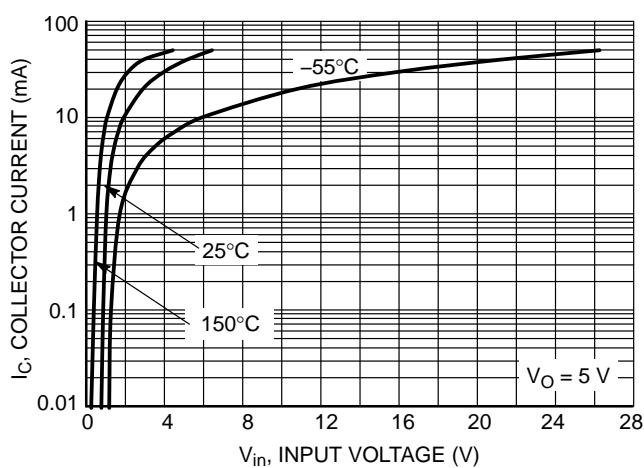
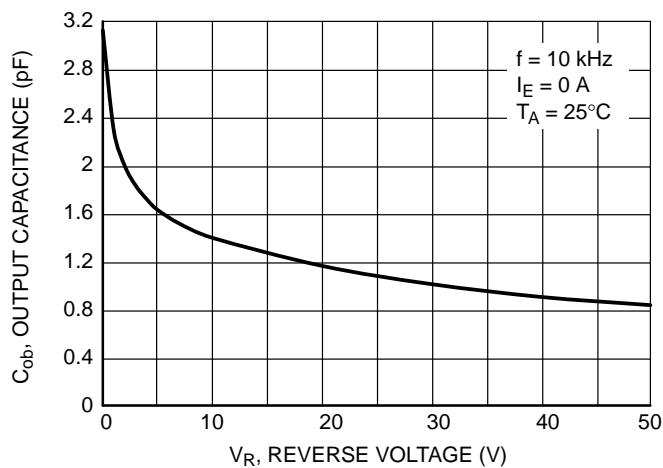
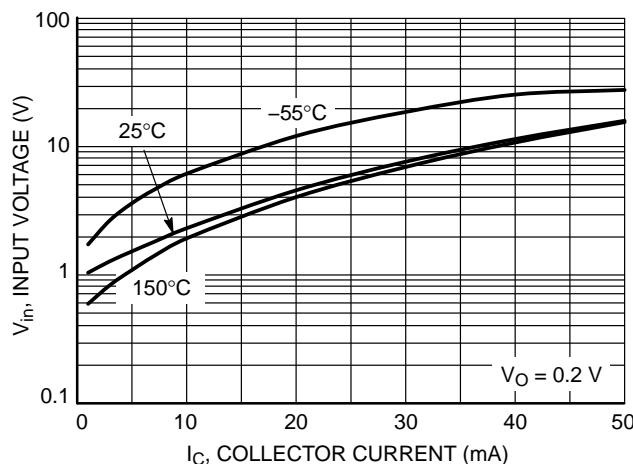
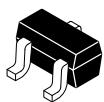


Figure 5. Output Current vs. Input Voltage

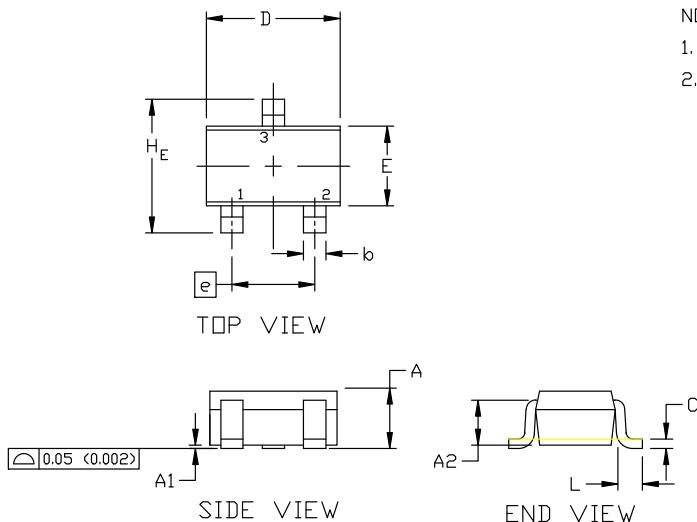




SCALE 4:1

SC-70 (SOT-323)  
CASE 419  
ISSUE R

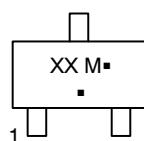
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## NOTES:

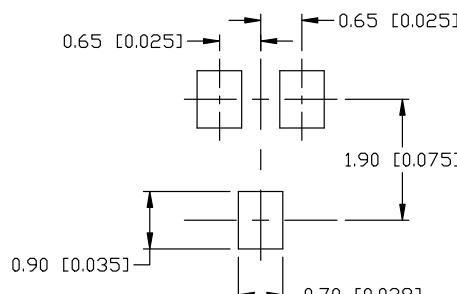
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH

DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 BSC		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.080	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
H_E	2.00	2.10	2.40	0.079	0.083	0.095

GENERIC  
MARKING DIAGRAM

XX = Specific Device Code  
M = Date Code  
■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.



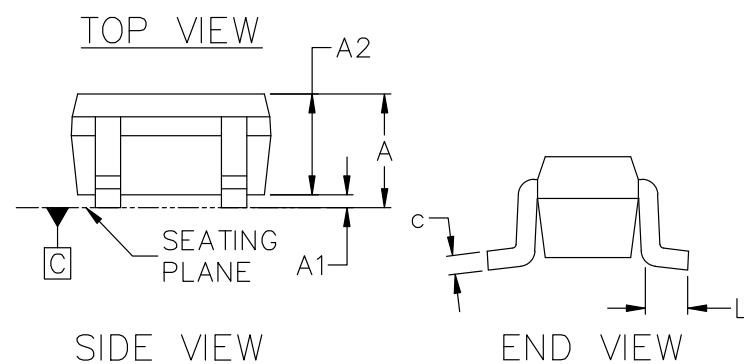
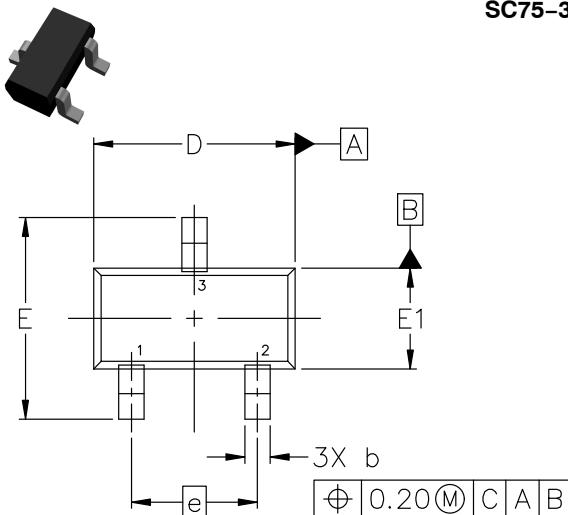
\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## SOLDERING FOOTPRINT

STYLE 1: CANCELLED	STYLE 2: PIN 1. ANODE 2. N.C. 3. CATHODE	STYLE 3: PIN 1. BASE 2. Emitter 3. Collector	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. CATHODE
STYLE 6: PIN 1. Emitter 2. BASE 3. COLLECTOR	STYLE 7: PIN 1. BASE 2. Emitter 3. Collector	STYLE 8: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 9: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. ANODE-CATHODE
				STYLE 11: PIN 1. CATHODE 2. CATHODE 3. CATHODE

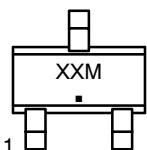
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DESCRIPTION:	SC-70 (SOT-323)	PAGE 1 OF 1

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SIDE VIEW

END VIEW

GENERIC  
MARKING DIAGRAM\*

XX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

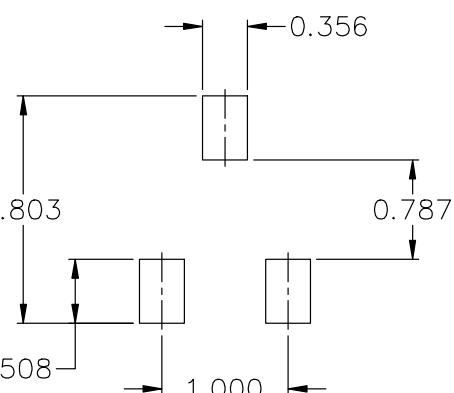
STYLE 1:  
PIN 1. BASE  
2. Emitter  
3. Collector

STYLE 2:  
PIN 1. ANODE  
2. N/C  
3. CATHODE

STYLE 3:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 4:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE

STYLE 5:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

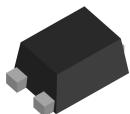


## RECOMMENDED MOUNTING FOOTPRINT\*

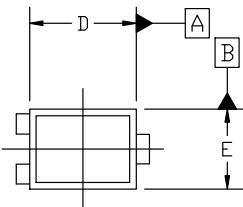
\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

DOCUMENT NUMBER:	98ASB15184C	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SC75-3 1.60x0.80x0.80, 1.00P	PAGE 1 OF 1

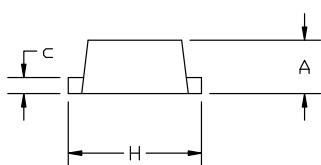
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**SOT-1123 0.80x0.60x0.37, 0.35P**  
CASE 524AA  
ISSUE D

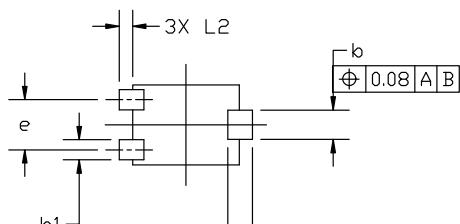
DATE 18 JAN 2024



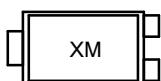
TOP VIEW



SIDE VIEW



BOTTOM VIEW

**GENERIC  
MARKING DIAGRAM\***


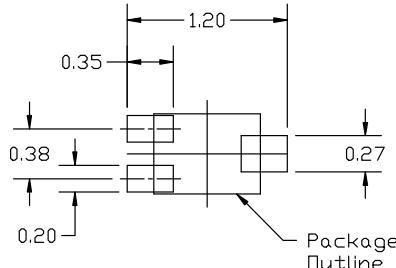
X = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.  
MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.34	0.37	0.40
b	0.15	0.22	0.28
b1	0.10	0.15	0.20
c	0.07	0.12	0.17
D	0.75	0.80	0.85
E	0.55	0.60	0.65
e	0.35	0.38	0.40
H	0.950	1.000	1.050
L	0.185 REF		
L2	0.05	0.10	0.15


**RECOMMENDED  
MOUNTING FOOTPRINT**

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual, SOLDERRM/D.

STYLE 1:  
PIN 1. BASE  
2. Emitter  
3. Collector

STYLE 2:  
PIN 1. ANODE  
2. N/C  
3. Cathode

STYLE 3:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 4:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE

STYLE 5:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

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DESCRIPTION:	SOT-1123 0.80x0.60x0.37, 0.35P	PAGE 1 OF 1

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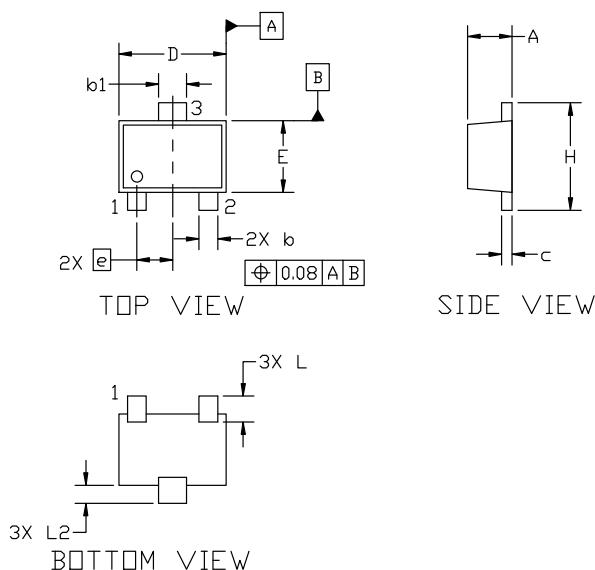


**SOT-723 1.20x0.80x0.50, 0.40P**  
CASE 631AA  
ISSUE E

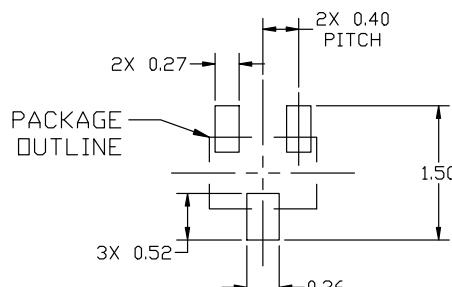
DATE 24 JAN 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



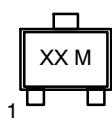
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.45	0.50	0.55
b	0.15	0.21	0.27
b1	0.25	0.31	0.37
c	0.07	0.12	0.17
D	1.15	1.20	1.25
E	0.75	0.80	0.85
e	0.40 BSC		
H	1.15	1.20	1.25
L	0.29 REF		
L2	0.15	0.20	0.25



RECOMMENDED MOUNTING  
FOOTPRINT

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC  
MARKING DIAGRAM\***



XX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:  
PIN 1. BASE  
2. Emitter  
3. Collector

STYLE 2:  
PIN 1. ANODE  
2. N/C  
3. CATHODE

STYLE 3:  
PIN 1. ANODE  
2. ANODE  
3. CATHODE

STYLE 4:  
PIN 1. CATHODE  
2. CATHODE  
3. ANODE

STYLE 5:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN

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